- Fast Transient Response Using Small Output Capacitor (10 μF)
- 200-mA Low-Dropout Voltage Regulator
- Available in 1.5-V, 1.8-V, 2.5-V, 3-V and 3.3-V
- Dropout Voltage Down to 170 mV at 200 mA (TPS7433)
- 3% Tolerance Over Specified Conditions
- 8-Pin SOIC Package
- Thermal Shutdown Protection

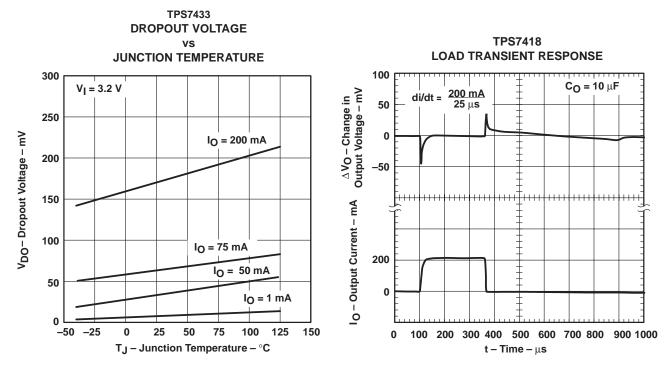
### description

D PACKAGE (TOP VIEW) EN **I**SENSE 8 Ι Ουτ NC Г 2 7 П NC 3 6 GND IN 4 5 IN NC - No internal connection

This device is designed to have a fast transient response and be stable with  $1-\mu F$  capacitors. This combination provides high performance at a reasonable cost.

Because the PMOS device behaves as a low-value resistor, the dropout voltage is very low (typically 170 mV at an output current of 200-mA for the TPS7433). This LDO family also features a sleep mode; applying a TTL high signal to  $\overline{EN}$  (enable) shuts down the regulator, reducing the quiescent current to less than 1  $\mu$ A at T<sub>J</sub> = 25°C.

The TPS74xx is offered in 1.5-V, 1.8-V, 2.5-V, 3-V, and 3.3-V. Output voltage tolerance is specified as a maximum of 3% over line, load, and temperature ranges. The TPS74xx family is available in 8 pin SOIC package.



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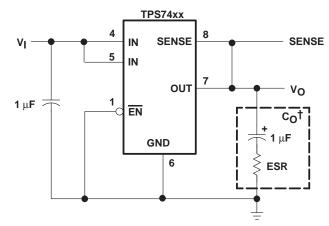


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#### AVAILABLE OPTIONS

т.	OUTPUT VOLTAGE (V)	PACKAGED DEVICES		
ТJ	ТҮР	SOIC (D)		
–40°C to 125°C	3.3	TPS7433D		
	3	TPS7430D		
	2.5	TPS7425D		
	1.8	TPS7418D		
	1.5	TPS7415D		

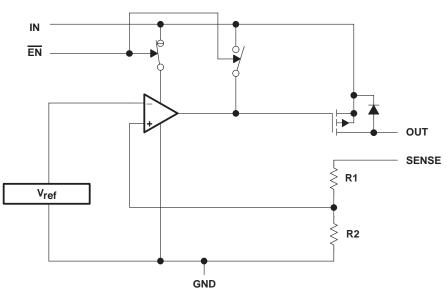
The D package is available taped and reeled. Add an R suffix to the device type (e.g., TPS7433DR).



<sup>†</sup> See application information section for capacitor selection details.

**Figure 1. Typical Application Configuration** 

### functional block diagram





### **Terminal Functions**

TERMIN	NAL	1/0	DESCRIPTION				
NAME	NO.	I/O	DESCRIPTION				
EN	1	I	Enable input				
GND	6		Regulator ground				
IN	4, 5	I	Input voltage				
NC	2, 3		Not connected				
OUT	7	0	Regulated output voltage				
SENSE	8	I	Sense				

### absolute maximum ratings over operating free-air temperature range (unless otherwise noted)<sup>†</sup>

Input voltage range <sup>‡</sup> , V <sub>I</sub>	
Peak output current	
Continuous total power dissipation	See dissipation rating tables
Operating virtual junction temperature range, T <sub>J</sub>	–40°C to 125°C
Storage temperature range, T <sub>stg</sub>	–65°C to 150°C

<sup>+</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

<sup>‡</sup> All voltage values are with respect to network terminal ground.

#### **DISSIPATION RATING TABLE 1 – FREE-AIR TEMPERATURES**

PACKAGE	CKAGE AIR FLOW T <sub>A</sub> < 25°C (CFM) POWER RATING		DERATING FACTOR ABOVE T <sub>A</sub> = 25°C	T <sub>A</sub> = 70°C POWER RATING	T <sub>A</sub> = 85°C POWER RATING	
	0	568 mW	5.68 mW/°C	312 mW	227 mW	
D	250	904 mW	9.04 mW/°C	497 mW	361 mW	

### recommended operating conditions

	MIN	MAX	UNIT
Input voltage, VIS	2.5	7	V
Output current, IO (see Note 1)	0	200	mA
Operating virtual junction temperature, T <sub>J</sub> (see Note 1)	-40	125	°C

§ To calculate the minimum input voltage for your maximum output current, use the following equation: V<sub>I(min)</sub> = V<sub>O(max)</sub> + V<sub>DO(max load)</sub>. NOTE 1: Continuous current and operating junction temperature are limited by internal protection circuitry, but it is not recommended that the device operate under conditions beyond those specified in this table for extended periods of time.



# electrical characteristics over recommended operating free-air temperature range, $V_i = V_{O(typ)} + 1 V$ , $I_O = 1 \text{ mA}$ , $\overline{EN} = 0 V$ , $C_O = 1 \mu F$ (unless otherwise noted)

PARAMETER		TEST CONDITIONS	TEST CONDITIONS	MIN	TYP	MAX	UNIT	
			TJ = 25°C		1.5			
	TPS7415	2.5 V < V <sub>I</sub> < 7 V	T <sub>J</sub> = -40°C to 125°C	1.455		1.545		
	TPS7418	2.8 V < V <sub>I</sub> < 7 V	Тј = 25°С		1.8		v	
			T <sub>J</sub> = -40°C to 125°C	1.746		1.854		
Output voltage (10 μA to 200 mA load)	TPS7425	251/21/271/	T <sub>J</sub> = 25°C		2.5			
(see Note 2)	11-3/423	3.5 V < V <sub>I</sub> < 7 V	$T_J = -40^{\circ}C$ to $125^{\circ}C$	2.425		2.575	v	
	TPS7430	4.0 V < V <sub>I</sub> < 7 V	TJ = 25°C		3.0			
	11 37430	4.0 V < V  < 7 V	$T_J = -40^{\circ}C$ to $125^{\circ}C$	2.910		3.090		
	TPS7433	4.3 V < V <sub>I</sub> < 7 V	TJ = 25°C		3.3			
	11 07 400	4.0 V V V V V V	T <sub>J</sub> = -40°C to 125°C	3.201		3.399		
		I <sub>O</sub> = 1 mA, EN = 0 V	TJ = 25°C		80		μA	
			$T_J = -40^{\circ}C$ to $125^{\circ}C$			115	μ	
Quiescent current (GND current) (See No	nte 2)	I <sub>O</sub> = 100 mA, EN = 0 V	TJ = 25°C		550		μA	
	,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,		$T_J = -40^{\circ}C$ to $125^{\circ}C$			850		
		I <sub>O</sub> = 200 mA, EN = 0 V	TJ = 25°C		1300		μA	
			$T_J = -40^{\circ}C$ to $125^{\circ}C$			1500		
Output voltage line regulation ( $\Delta V_O/V_O$ ) (see Notes 2 and 3)		$V_{O} + 1 V < V_{I} \le 7 V$ ,	$T_J = 25^{\circ}C$		0.06		%/V	
Load regulation					5		mV	
Output noise voltage		BW = 300 Hz to 50 kHz, T <sub>J</sub> = $25^{\circ}$ C	C <sub>O</sub> = 1 μF,		190		μVrm	
Output current Limit		V <sub>O</sub> = 0 V			500	750	mA	
Thermal shutdown junction temperature			:		150		°C	
Standby current		2.5 V < V <sub>I</sub> < 7 V, T <sub>J</sub> = 25°C	EN = VI,			1	μA	
		2.5 V < V <sub>I</sub> < 7 V, T <sub>J</sub> = -40°C to 125°C	EN = VI,			3	μΑ	
High level enable input voltage				2			V	
Low level enable input voltage						0.7	V	
Input current (EN)		EN = 0 V		-1		1	1 1 μΑ	
		EN = VI		-1		1		
Power supply ripple rejection (see Note 2)		f = 100 Hz, TJ = 25°C	$C_{O} = 1 \ \mu F$ ,		55		dB	
		I <sub>O</sub> = 200 mA,	Тј = 25°С		180		+	
	TPS7430	$I_0 = 200 \text{ mA},$	T <sub>J</sub> = -40°C to 125°C			350	1.	
Dropout voltage (see Note 4)		$I_{O} = 200 \text{ mA},$	TJ = 25°C		170		mV	
	TPS7433	$I_0 = 200 \text{ mA},$	T <sub>J</sub> = -40°C to 125°C			315	15	

NOTES: 2. Minimum IN operating voltage is 2.5 V or VO(typ) + 1 V, whichever is greater. Maximum IN voltage 7 V.

3. If  $V_O = 1.5$  V then  $V_{imax} = 7$  V,  $V_{imin} = 2.5$  V:

IN voltage equals V<sub>O</sub>(Typ) – 100 mV; TPS7430 and TPS7433 dropout limited by input voltage range limitations (i.e., TPS7430 input voltage needs to drop to 2.9 V for purpose of this test).

Line Reg. (mV) = 
$$(\%/V) \times \frac{V_O(V_{imax} - 2.5 V)}{100} \times 1000$$

If  $V_O \ge 2.5$  V then  $V_{imax} = 7$  V,  $V_{imin} = V_O + 1$  V:

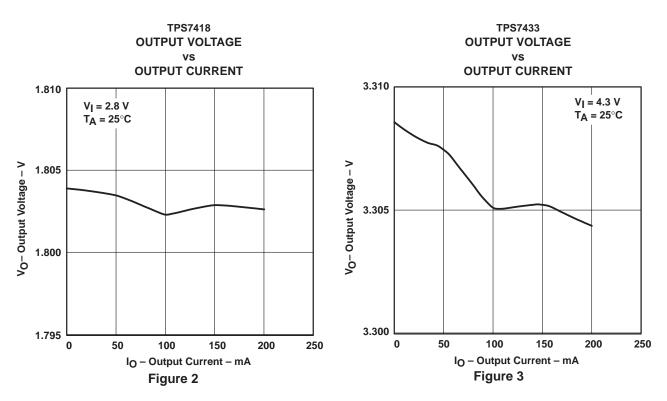
Line Reg. (mV) = 
$$(\%/V) \times \frac{V_O(V_{imax} - (V_O + 1 V))}{100} \times 1000$$



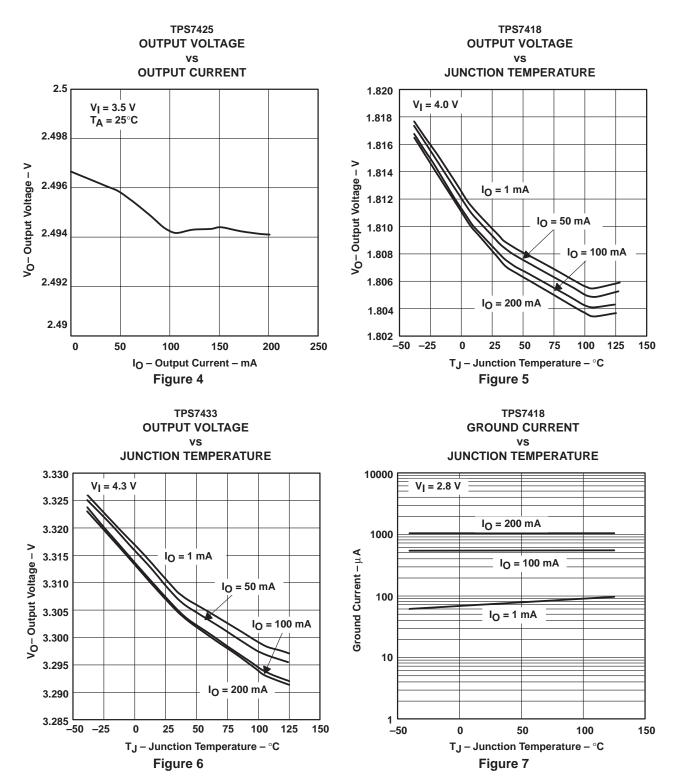
### **Table of Graphs**

			FIGURE
Vo	Output valence	vs Output current	2, 3, 4
	Output voltage	vs Junction temperature	5, 6
	Ground current	vs Junction temperature	7, 8
	Power supply ripple rejection	vs Frequency	12
	Output noise	vs Frequency	9
Z <sub>0</sub>	Output impedance	vs Frequency	10
V <sub>DO</sub>	Dropout voltage	vs Junction temperature	11
	Line transient response		13, 15
	Load transient response		14, 16
	Output voltage	vs Time	17
	(Stability) Equivalent series resistance (ESR)	vs Output current	19



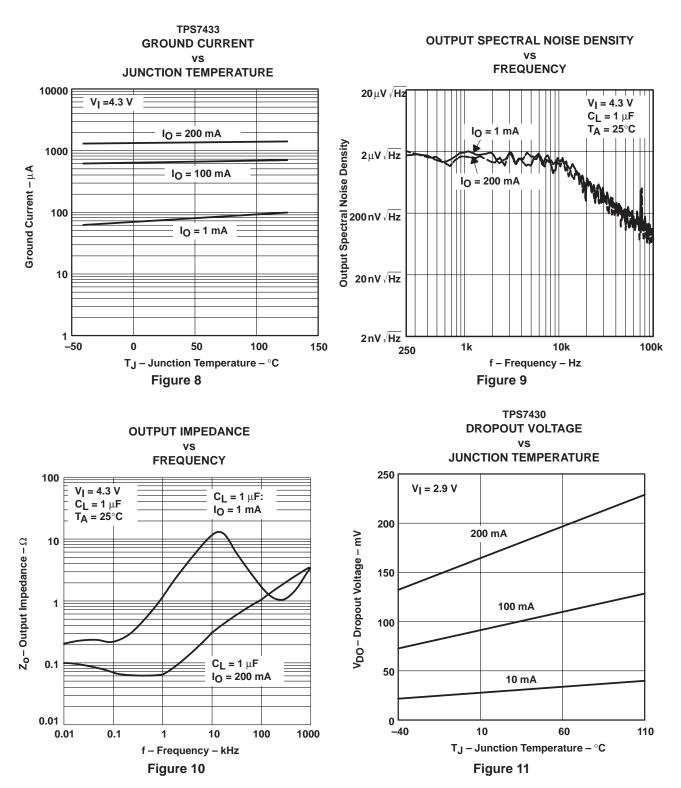






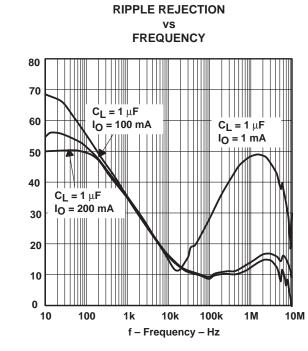


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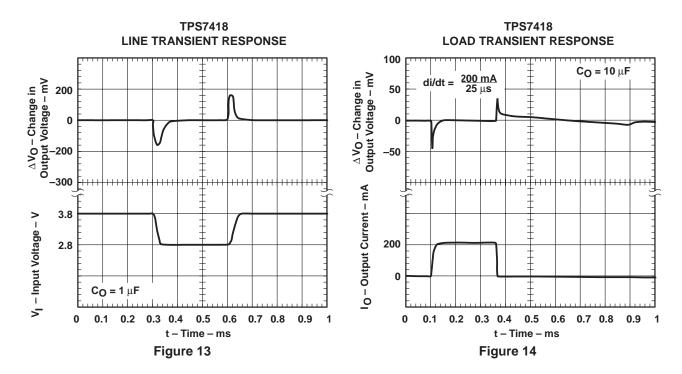




Ripple Rejection – dB

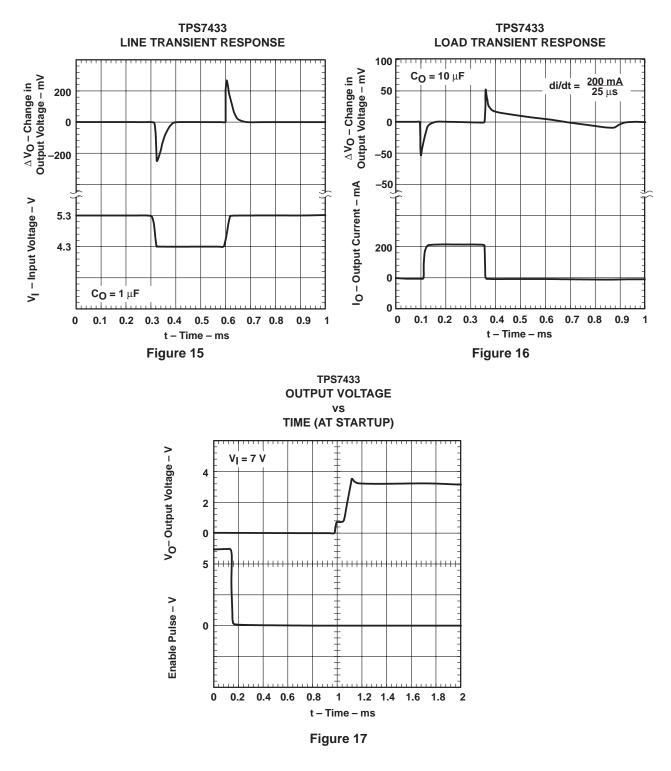






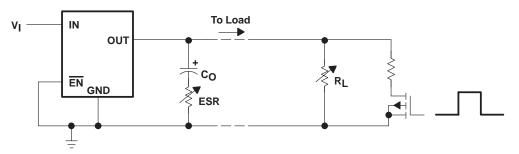




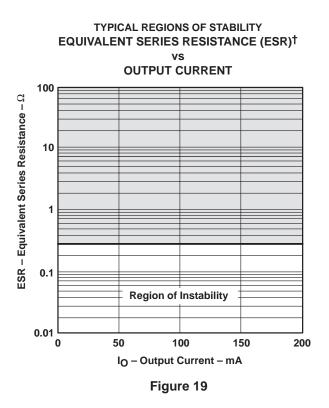




### **TYPICAL CHARACTERISTICS**







<sup>†</sup> ESR refers to the total series resistance, including the ESR of the capacitor, any series resistance added externally, and PWB trace resistance to C<sub>O</sub>.



### **APPLICATION INFORMATION**

The TPS74xx family includes five voltage regulators (1.5 V, 1.8 V, 2.5 V, 3 V, and 3.3 V).

#### minimum load requirements

The TPS74xx family is stable even at zero load; no minimum load is required for operation.

### SENSE terminal connection

The SENSE terminal must be connected to the regulator output for proper functioning of the regulator. Normally, this connection should be as short as possible; however, the connection can be made near a critical circuit (remote sense) to improve performance at that point. Internally, SENSE connects to a high-impedance wide-bandwidth amplifier through a resistor-divider network and noise pickup feeds through to the regulator output. Routing the SENSE connection to minimize/avoid noise pickup is essential. Adding an RC network between SENSE and OUT to filter noise is not recommended because it can cause the regulator to oscillate.

### external capacitor requirements

An input capacitor is not usually required; however, a ceramic bypass capacitor (1 uF or larger) improves load transient response and noise rejection if the TPS74xx is located more than a few inches from the power supply. A higher-capacitance electrolytic capacitor may be necessary if large (hundreds of milliamps) load transients with fast rise times are anticipated.

Like all low dropout regulators, the TPS74xx requires an output capacitor connected between OUT and GND to stabilize the internal control loop. The minimum recommended capacitance value is 1 uF and the ESR (equivalent series resistance) must be at least 300 m $\Omega$ . Solid tantalum electrolytic and aluminum electrolytic are all suitable, provided they meet the requirements described previously.

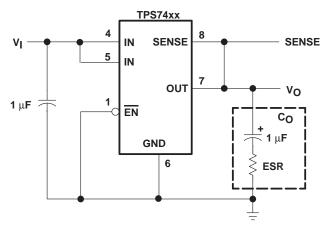


Figure 20. Typical Application Circuit

#### regulator protection

The TPS74xx PMOS-pass transistor has a built-in back diode that conducts reverse currents when the input voltage drops below the output voltage (e.g., during power down). Current is conducted from the output to the input and is not internally limited. When extended reverse voltage is anticipated, external limiting may be appropriate.



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### **APPLICATION INFORMATION**

### regulator protection (continued)

The TPS74xx also features internal current limiting and thermal protection. During normal operation, the TPS74xx limits output current to approximately 500 mA. When current limiting engages, the output voltage scales back linearly until the overcurrent condition ends. While current limiting is designed to prevent gross device failure, care should be taken not to exceed the power dissipation ratings of the package. If the temperature of the device exceeds 150°C(typ), thermal-protection circuitry shuts it down. Once the device has cooled below 130°C (typ), regulator operation resumes.

### power dissipation and junction temperature

Specified regulator operation is assured to a junction temperature of 125°C; the maximum junction temperature should be restricted to 125°C under normal operating conditions. This restriction limits the power dissipation the regulator can handle in any given application. To ensure the junction temperature is within acceptable limits, calculate the maximum allowable dissipation, PD(max), and the actual dissipation, PD, which must be less than or equal to PD(max).

The maximum-power-dissipation limit is determined using the following equation:

$$P_{D(max)} = \frac{T_J max - T_A}{R_{\theta JA}}$$

Where

T<sub>.1</sub>max is the maximum allowable junction temperature.

 $R_{\theta JA}$  is the thermal resistance junction-to-ambient for the package, i.e., 172°C/W for the 8-terminal SOIC.

T<sub>A</sub> is the ambient temperature.

The regulator dissipation is calculated using:

 $P_{D} = (V_{I} - V_{O}) \times I_{O}$ 

Power dissipation resulting from quiescent current is negligible. Excessive power dissipation will trigger the thermal protection circuit.

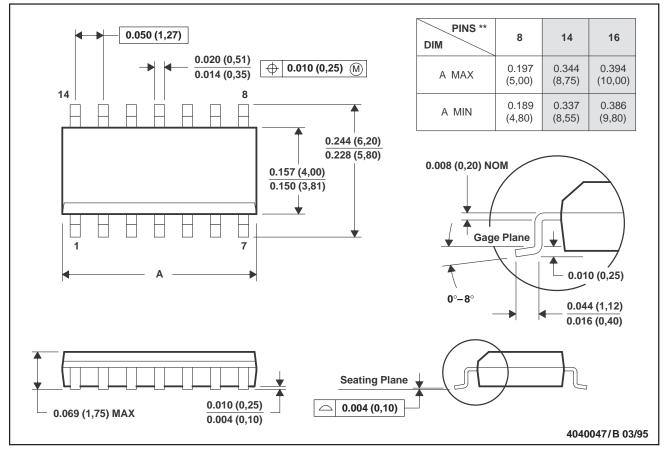


MECHANICAL DATA

#### PLASTIC SMALL-OUTLINE PACKAGE

### D (R-PDSO-G\*\*)





NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

- C. Body dimensions do not include mold flash or protrusion, not to exceed 0.006 (0,15).
- D. Four center pins are connected to die mount pad.
- E. Falls within JEDEC MS-012



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